



Solder wire

ı-Flex 400 SnPb

INTERFLUX®
ELECTRONICS N.V.



Technical data ı-Flex 400 SnPb
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Very low residue, no-clean and halide free solder wire

Description:

Interflux® ı-Flex 400 SnPb is a no-clean solder wire with a chemically modified rosin that has been developed to give very low residue formation.

The flux inside of the wire facilitates a quick and clean soldering process, making it the best choice for intensive hand soldering operations as well as for automated soldering (robot soldering).

ı-Flex 400 SnPb has good wetting properties on virtually all standard surface finishings in electronics assembly.

The residues after soldering are minimal and a hand soldered solder joint can hardly be distinguished from a wave soldered or reflowed solder joint.

Moreover, ı-Flex 400 SnPb is absolutely halogen free, providing for very safe residues after soldering.

ı-Flex 400 SnPb is classified as RO/L0 according IPC J-STD-004A.



Products pictured may differ from the product delivered

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Key advantages:

- Very low residue
- Absolutely halogen free
- Long tip life

Availability

Flux type: ı-Flex 400 SnPb
Flux content: 0,9% w/w 1,4% w/w

alloy	melting point	diameters					
		0,35	0,50	0,70	1,00	1,50	2,00
Sn60Pb40	183°C–191°C	●	●	●	●	●	●
Sn63Pb37	183°C	●	●	●	●	●	●
Sn62Pb36Ag2	179°C	●	●	●	●	●	●

● = available ● = upon request



Work instructions

Manual soldering

The working temperature is between 320°C and 360°C. For more dense metals like Nickel, the temperature may be elevated to 400°C.

Choose the correct soldering tip: to reduce the thermal resistance, it is important to create a large contact surface with the component

and solder pad.

The use of a good soldering station is important in order to always have the correct temperature on the soldering joint. Use a soldering station with a response time as short as possible.

Heat up the surfaces of both component and island simultaneously. Slightly touch with the solder wire,

the point where component lead, soldering island and soldering tip meet (the small quantity of solder ensures a drastic lowering of the thermal resistance). Add subsequently without interruption, the correct amount of solder close to the soldering tip without touching the tip. It is important that no solder wire is making contact with

the soldering tip during soldering to avoid flux spitting and premature flux consumption!

Handling

Storage

Store the solder wire in a clean environment at ambient temperature

Handling

To avoid spool and wire damage, handle package with care.

Safety

Please always consult the safety data-sheet of the product.



Test results

conform IPC J-STD-004A

Property	Result	Method
Chemical		
flux designator	RO L0	J-STD-004A
	F-SW 32	DIN 8511
	1.1.3	ISO 9454
qualitative copper mirror	pass	J-STD-004A IPC-TM-650 2.3.32
qualitative halide		
silver chromate (Cl, Br)	pass	J-STD-004A IPC-TM-650 2.3.33
spot test (F)	pass	J-STD-004A IPC-TM-650 2.3.35.1
quantitative halide	0,00%	J-STD-004A IPC-TM-650 2.3.35
Environmental		
SIR test	pass	J-STD-004A IPC-TM-650 2.6.3.3
qualitative corrosion, flux	pass	J-STD-004A IPC-TM-650 2.6.15



Packaging

Spools of 100g, 500g and 1000g



Trade name : \checkmark -Flex 400 SnPb, Halide Free, No-Clean Solder Wire

D i s c l a i m e r

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